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# Virtual Event

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## Drive More Than Two Pin Levels With DPU-16

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**TERADYNE**

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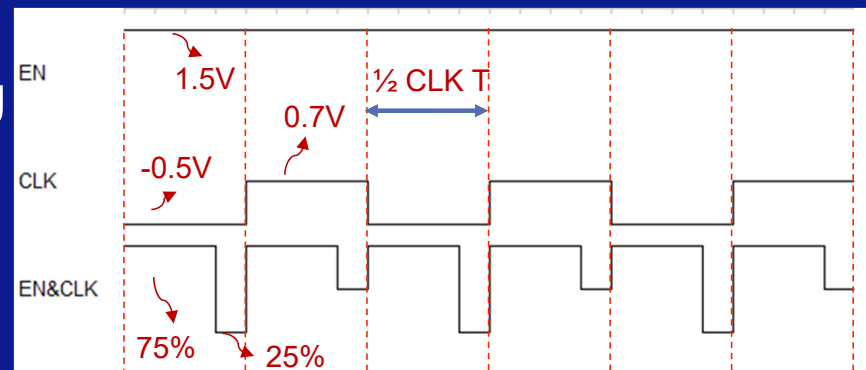
Drive More Than Two Pin Levels With DPU-16

2022

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## Background and Requirements

- With the fast development of semiconductor technology in the world, there's a tendency to reduce the device size and redundant pin count.
- A device pin combines EN pin and CLK pin to limit the pin count in scan chain structure.
- The combined signal drives three levels in total, normally we use DPU to drive high/low, that is 2 levels
- 0-75% of each period is EN signal, 75%-100% is CLK signal



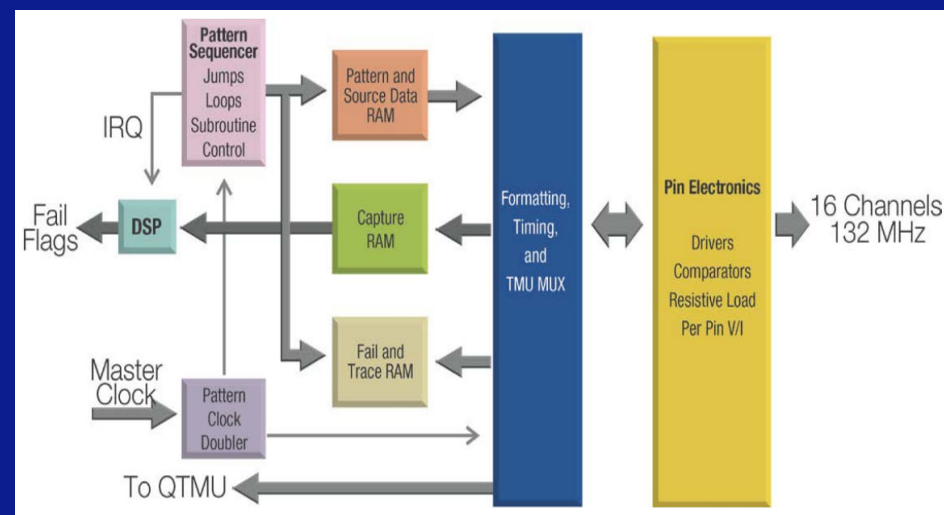
## Introduction of ETS-88

- ETS-88 is a mixed signal automated testing environment, testing a wide variety of devices including: simple analog, high precision, high voltage, high current / power, automotive etc.
- Eagle test system offers high throughput, low cost for Single site, Multi-site and Index Parallel Applications



## Introduction of DPU-16 board

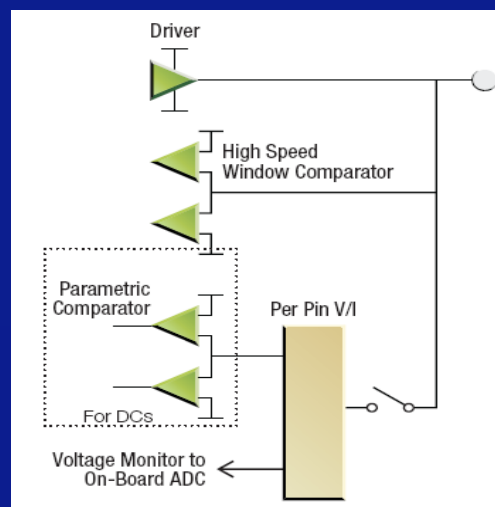
- DPU-16 is a commonly used instrument for digital tests
- It provides 16 full-featured digital I/O channels
- Supporting vector rates up to 132 MHz(DDR mode)



DPU-16 Block Diagram

## Pin Electronics

- Independent programmable drive and receive levels per pin
- Drive pin state: 0, 1, T, Z
- Receive pin state: H, L, X, V, M

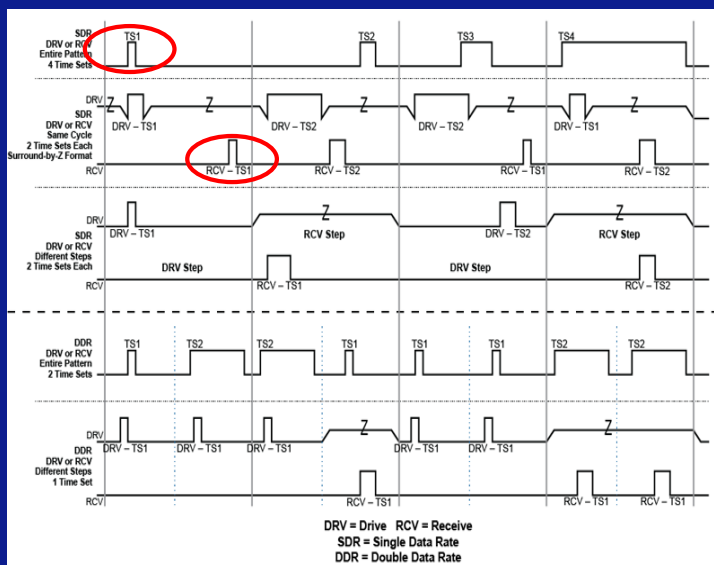


Pin Electronics Diagram

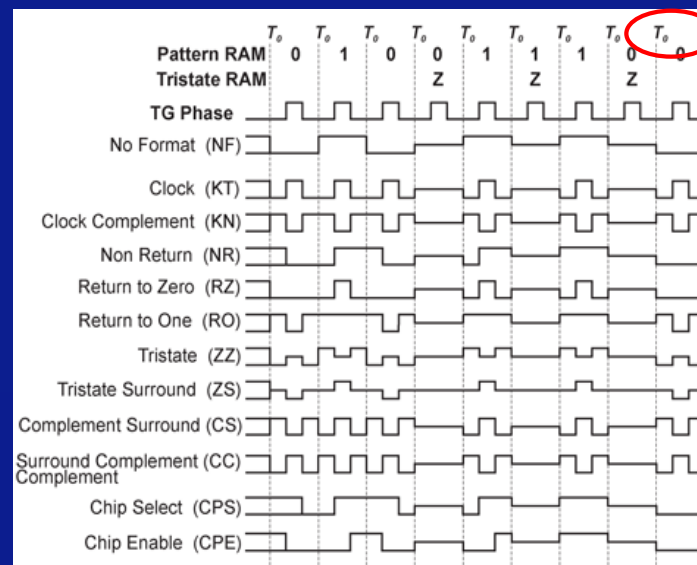


## Data Format and Edge setting

- Data format: specify the level change within a period
- Edge set : specify when to have the level change



Timeset Application for DPU-16 Pin Modes



DPU-16 Digital Data Formats

T0: Period  
Clock,  
generate  
the timing  
reference

Drive More Than Two Pin Levels With DPU-16

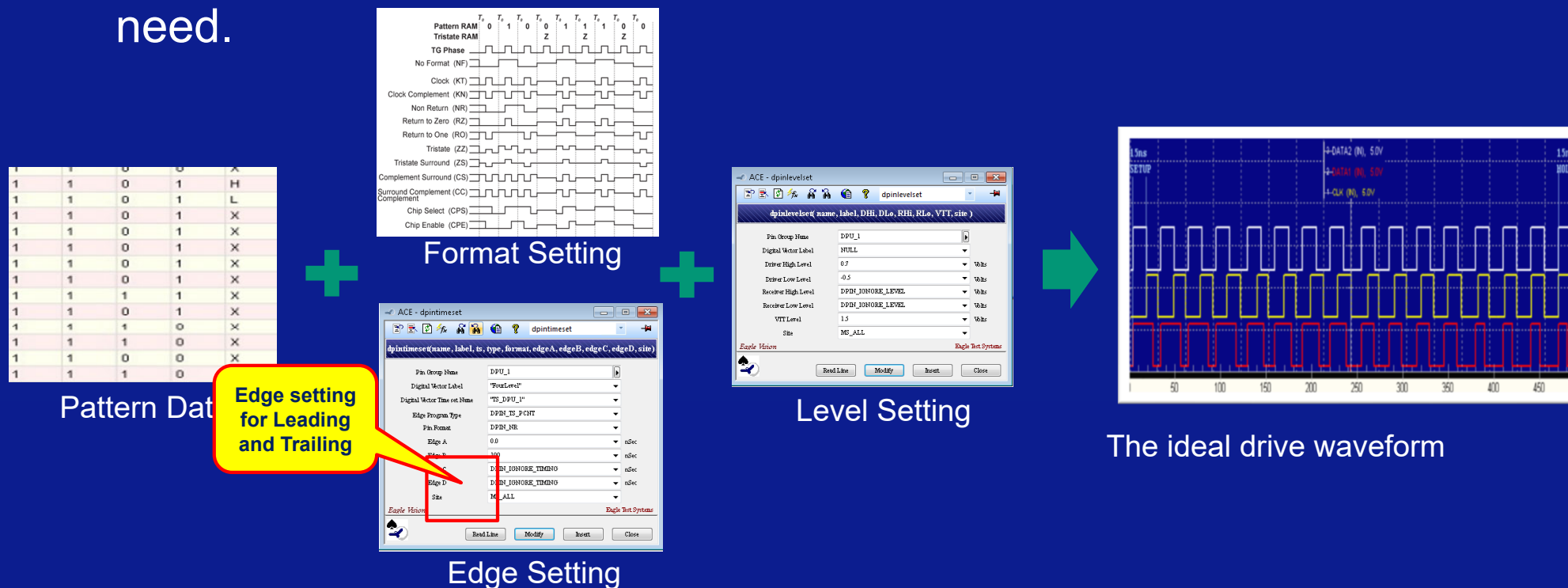
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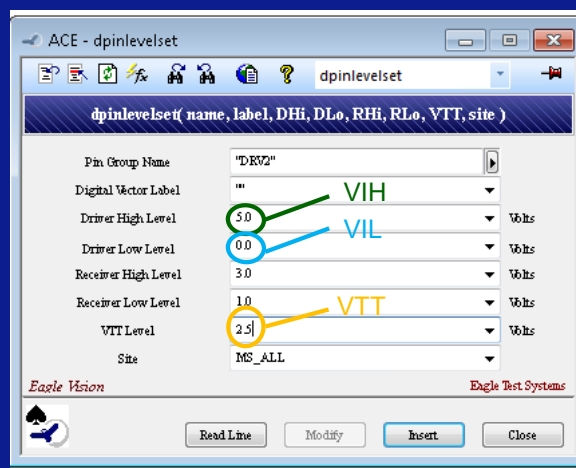
## Drive the Waveform

- With PE, combine the settings to get the actual drive waveform we need.



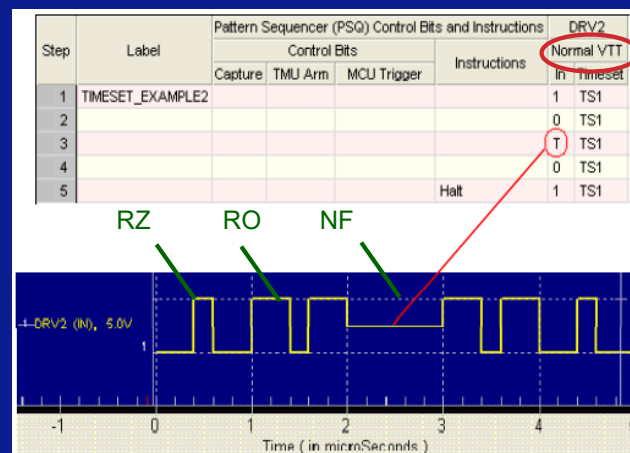
## VTT Drive Mode(the 3<sup>rd</sup> Level)

- Three drive levels: drive high, drive low, VTT level
- VTT level is 50  $\Omega$  output impedance, -1.0 to +7.0 V
- **Restrict:** format is not available on VTT level



Level Setting

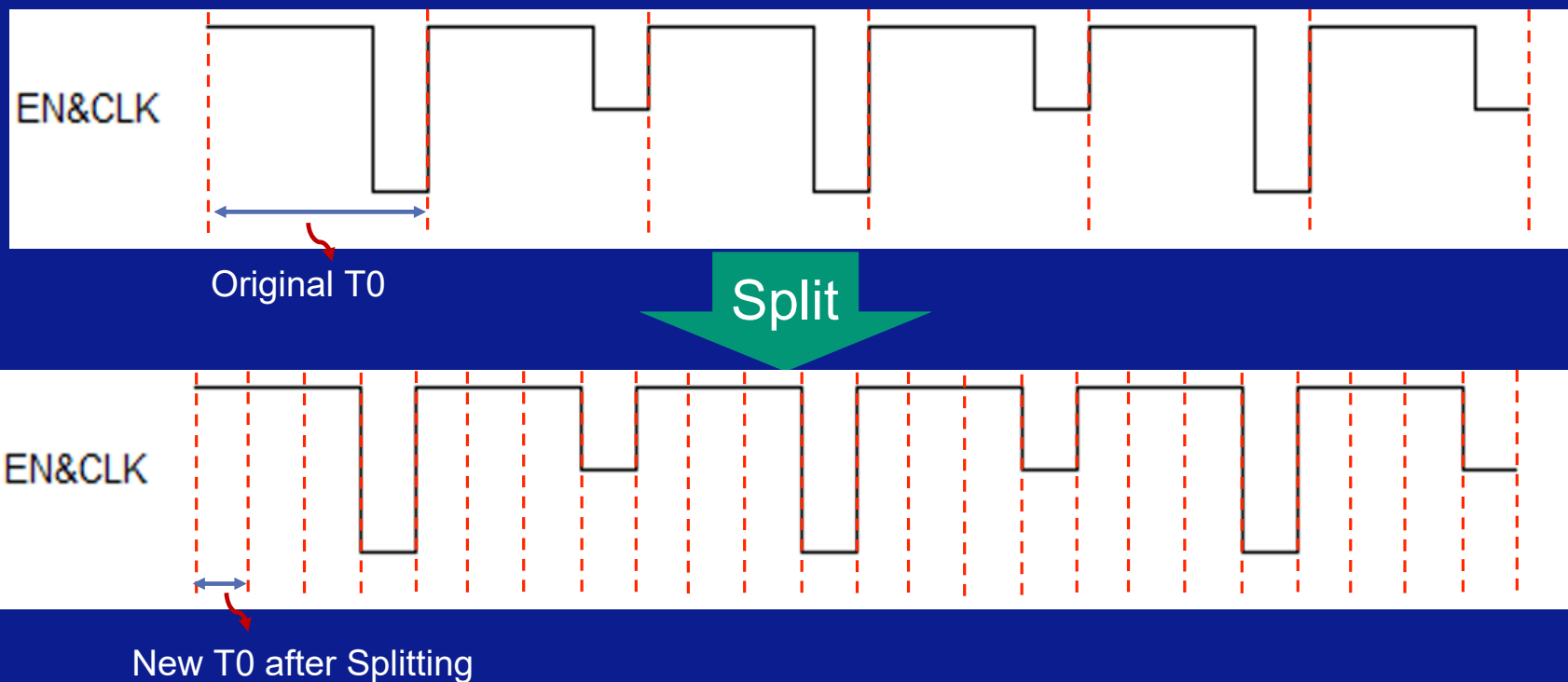
Define Pin as  
VTT type



VTT Mode Setting in Pattern

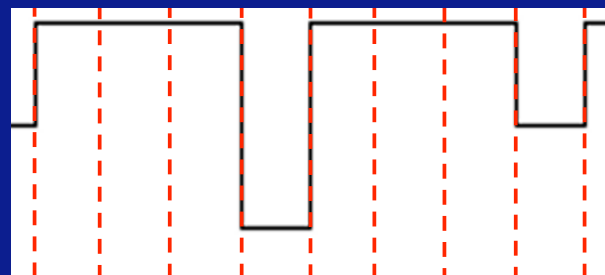
## Method 1: Split Period

- T0: split x4



## Method 1: Split Period

- Pattern to describe the waveform



T T T 0 T T T 1

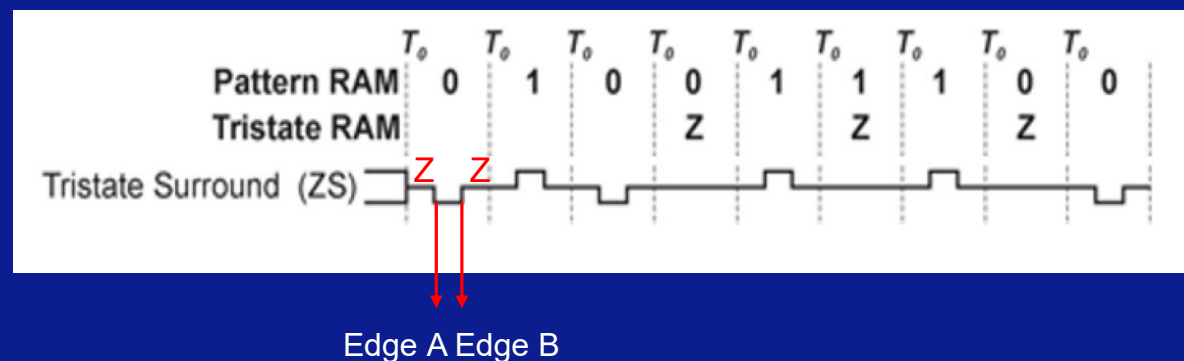
Step	Label	Pattern Sequencer (PSQ) Control Bits and Instructions				DPU_1 Normal VTT In/Out	Comments
		Capture	TMU Arm	MCU Trigger	Instructions		
1	Three levels_div4					T	
2						T	
3						T	
4						0	
5						T	
6						T	
7						T	
8						1	
9						T	
10						T	
11						T	
12						0	
13						T	
14						T	
15						T	
16						1	
17						T	
18						T	
19						T	
20						0	

- Restrict: Need more store memory. Need to translate the pattern data.

Is it possible to drive the levels with original T0? **Yes!**

## Method 2: With Format Tristate Surround(ZS)

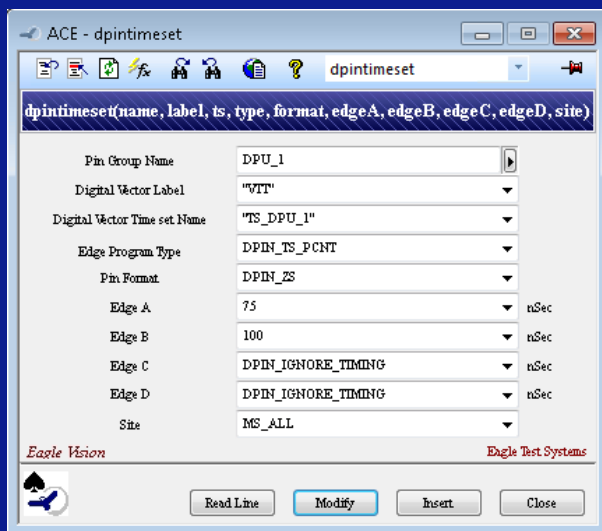
- The format *Tristate Surround* means the level before edge A and after edge B is set to Z(VTT level) .



- In our case, we can set the edge A to 75% of the whole period, edge B as the end of a period.

## Method 2: With Format Tristate Surround(ZS)

- No need to split T0, save store memory.
- No need to translate the data, easy to create the pattern data.

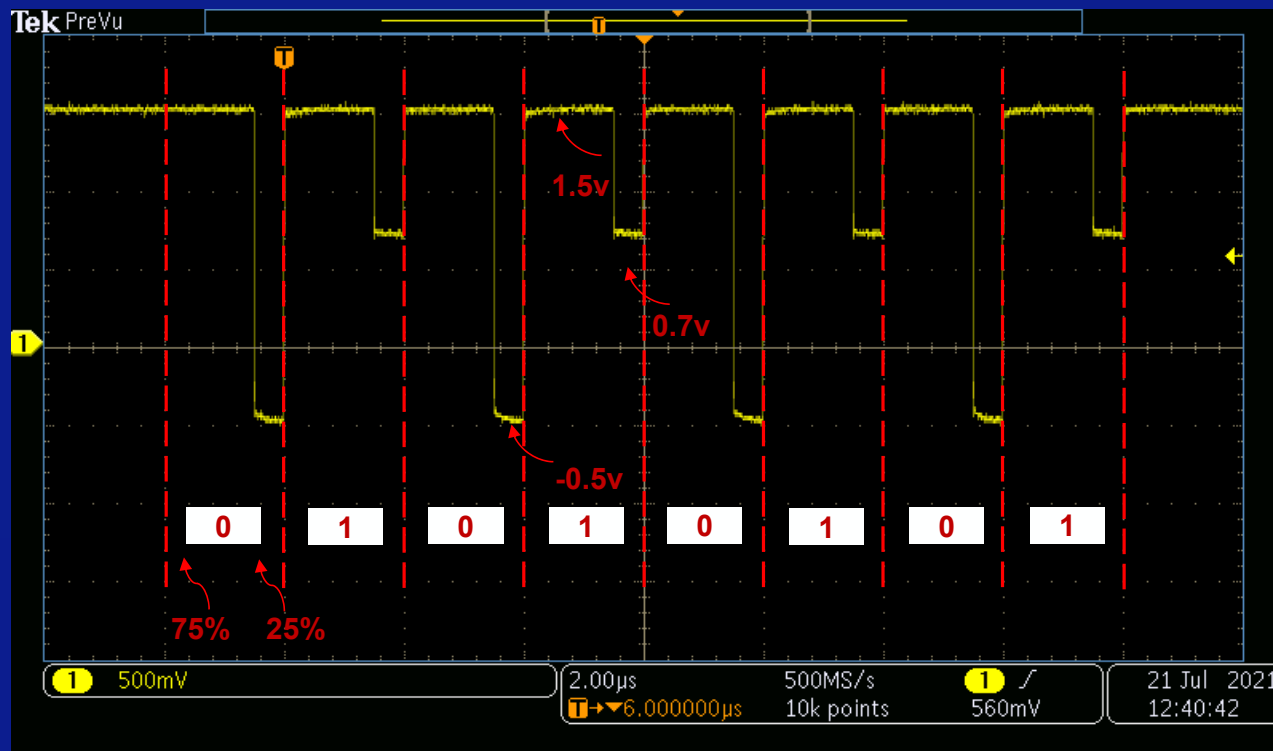


Format and Edge Setting

Step	Label	Pattern Sequencer (PSQ) Control Bits and Instructions				DPU_1	Comments
		Control Bits			Instructions	Normal VTT	
		Capture	TMU Arm	MCU Trigger		InOut	
1	VTT					0	
2						1	
3						0	
4						1	
5						0	
6						1	
7						0	
8					Halt	1	

Pattern Data

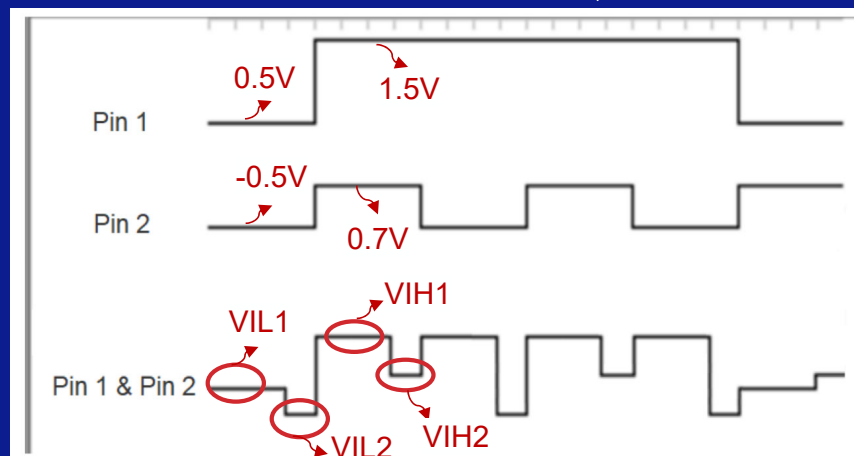
## Actual waveform





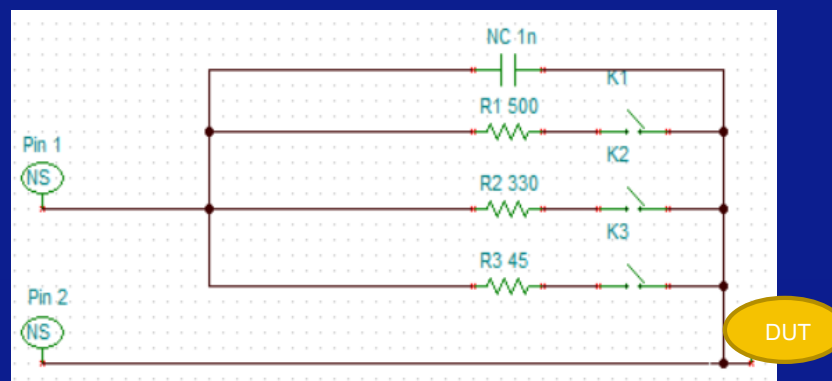
## Drive More than 3 Levels

- One more complexed case:
  - One device pin combines pin1 and pin2
  - VIL1 and VIH1 on pin1, VIL2 and VIH2 on pin2
  - the combined signal drives four levels in total
  - One DPU channel can't achieve, take into two DPU channels



## Block Diagram

- Pin1 and Pin2 connect R to device pin
- Pin1 drive VIL1, VIH1 while Pin2 drive Hiz
- Pin2 drive VIL2, VIH2 while Pin1 drive Hiz



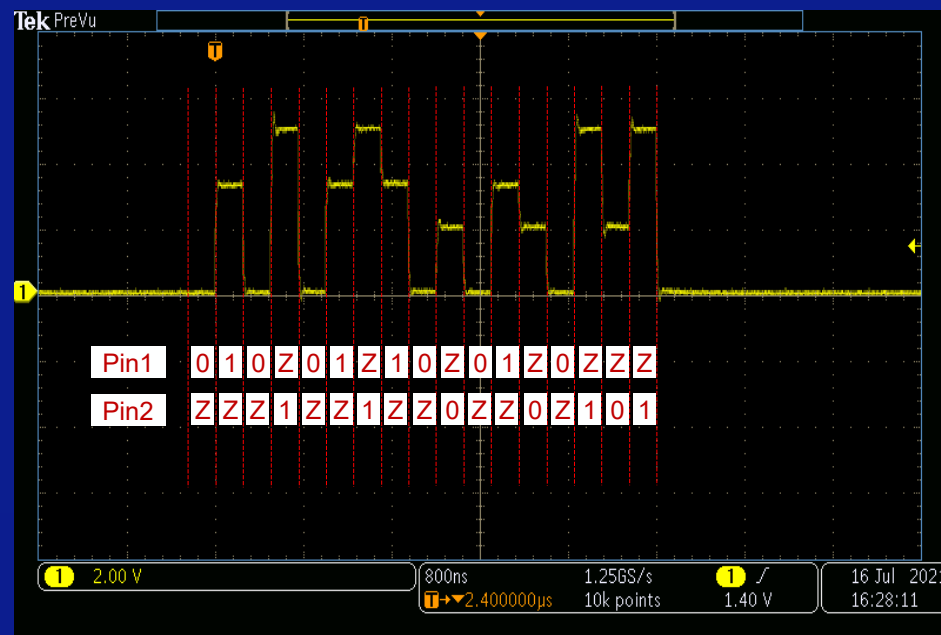
Block Diagram

## Pattern and Waveform

- One more complex vector data needed

Step	Label	Pattern Sequencer (PSQ) Control Bits and Instructions				Pin1		Pin2		Comments
		Control Bits			Instructions	Normal		Normal		
		Capture	TMU Arm	MCU Trigger		In/Out	Timeset	In	Timeset	
1	FourLevel					0	TS_Pin1	Z	TS_Pin2	V1
2						1	TS_Pin1	Z	TS_Pin2	V2
3						0	TS_Pin1	Z	TS_Pin2	V1
4						Z	TS_Pin1	1	TS_Pin2	V4
5						0	TS_Pin1	Z	TS_Pin2	V1
6						1	TS_Pin1	Z	TS_Pin2	V2
7						Z	TS_Pin1	1	TS_Pin2	V4
8						1	TS_Pin1	Z	TS_Pin2	V2
9						0	TS_Pin1	Z	TS_Pin2	V1
10						Z	TS_Pin1	0	TS_Pin2	V3
11						0	TS_Pin1	Z	TS_Pin2	V1
12						1	TS_Pin1	Z	TS_Pin2	V2
13						Z	TS_Pin1	0	TS_Pin2	V3
14						0	TS_Pin1	Z	TS_Pin2	V1
15						Z	TS_Pin1	1	TS_Pin2	V4
16						Z	TS_Pin1	0	TS_Pin2	V3
17						Z	TS_Pin1	1	TS_Pin2	V4
18					Halt	0	TS_Pin1	0	TS_Pin2	V1

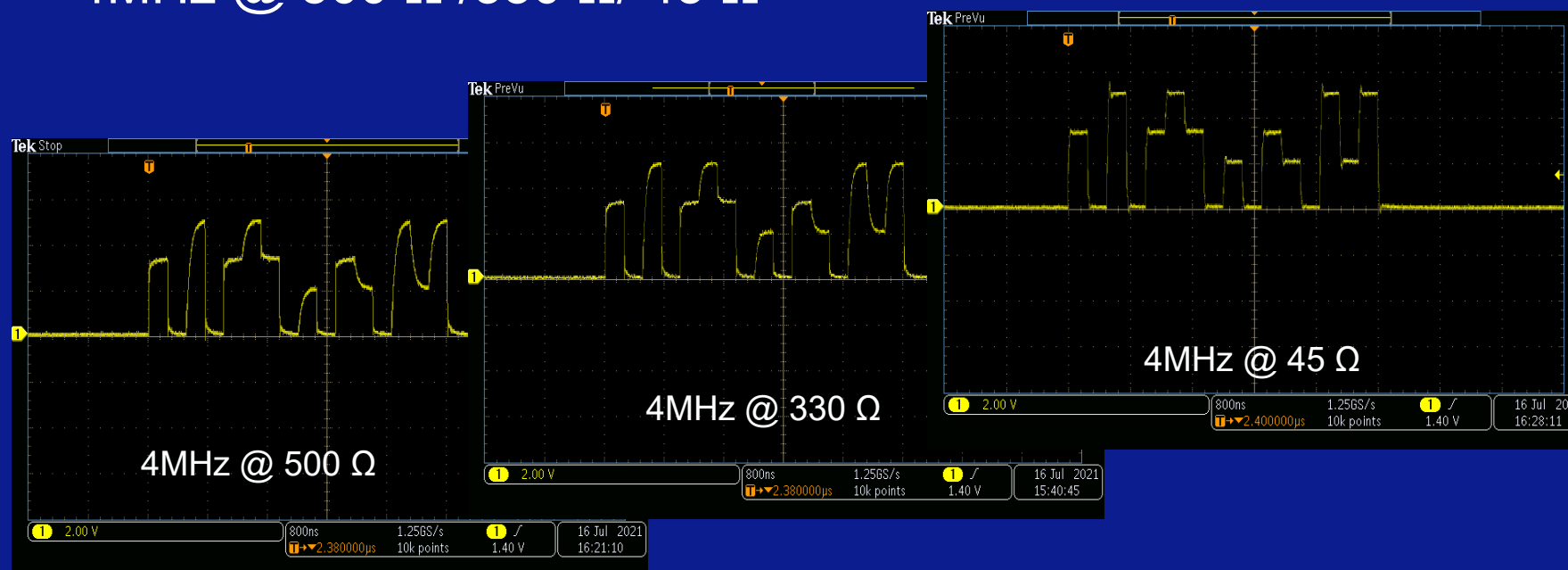
Pattern to Drive Four Levels



Actual Waveform

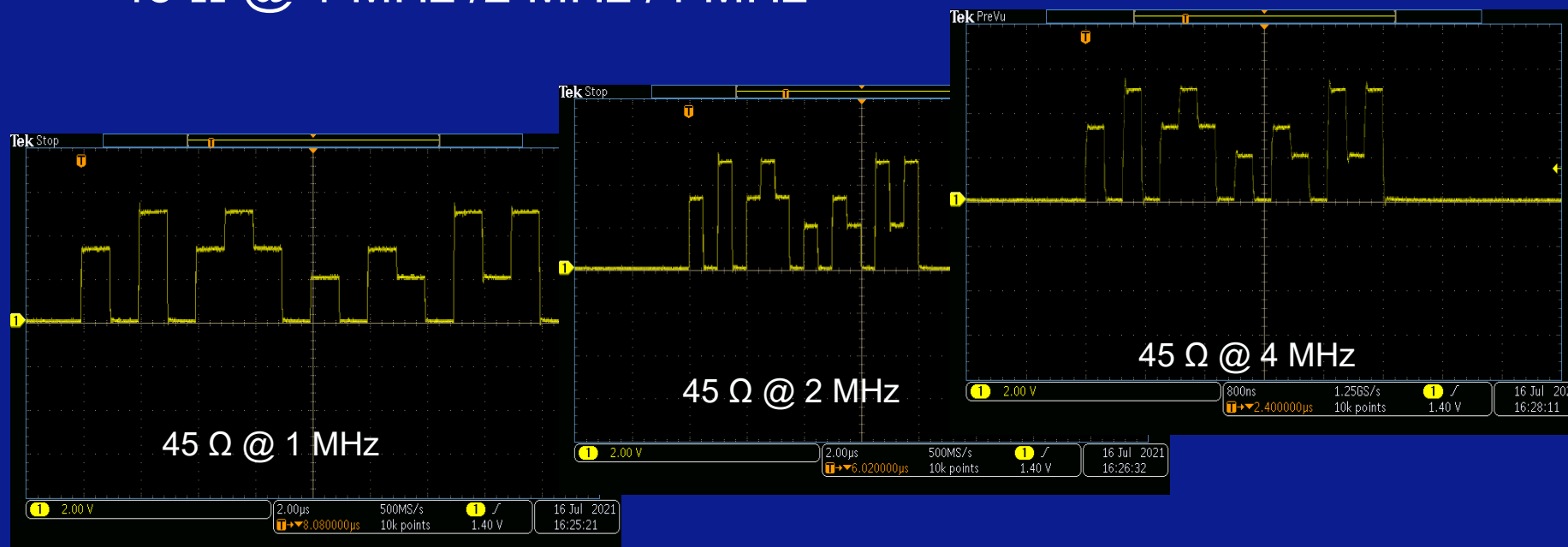
## Actual Waveform

- 4MHz @ 500  $\Omega$  / 330  $\Omega$  / 45  $\Omega$



## Actual Waveform

- $45\ \Omega$  @ 1 MHz / 2 MHz / 4 MHz



## Something Need to Add

- The higher the resistance is, the slower the signal rises/falls
- Resistor select suitable value to fit impedance matching
- Resistor connects to device as close as possible to reduce spikes when high speed signal

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